

Title (en)  
Balance-spring resonator spiral

Title (de)  
Spiralfeder der Resonatorunruh

Title (fr)  
Spiral de résonateur balancier-spiral

Publication  
**EP 1655642 A2 20060510 (FR)**

Application  
**EP 06003086 A 20040202**

Priority  
• EP 04707219 A 20040202  
• EP 03075362 A 20030206  
• EP 06003086 A 20040202

Abstract (en)  
The hairspring has a center curve (11) with an end including a self-locking washer forming a collet. The washer has a triangular contour (19) in its center to allow fixing of the hairspring to a shaft of a balance wheel. An external contour of the washer is closed and an inner wall of the contour (19) has a series of discrete elastic zones that are defined by openings (18) formed across the washer at right side of the zones.

IPC 8 full level  
**G04B 17/34** (2006.01); **G04B 17/06** (2006.01); **G04D 3/00** (2006.01)

CPC (source: EP KR US)  
**G04B 17/066** (2013.01 - EP KR US); **G04B 17/34** (2013.01 - US); **G04B 17/345** (2013.01 - EP KR US); **G04D 3/0041** (2013.01 - EP KR US); **G04D 3/0069** (2013.01 - EP KR US)

Citation (applicant)  
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